

54ACT16821, 74ACT16821 20-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS176A – JANUARY 1991 – REVISED APRIL 1996

- Members of the Texas Instruments *Widebus*™ Family
- Inputs Are TTL-Voltage Compatible
- Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- *EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- Package Options Include 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

These 20-bit flip-flops feature 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, parity bus interfacing, and working registers.

The 'ACT16821 can be used as two 10-bit flip-flops or one 20-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs follow the data (D) inputs. Each 10-bit flip-flop section has a buffered output-enable (1OE or 2OE) input that can be used to place the ten outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

$\overline{OE}$ does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16821 is packaged in the TI shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16821 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16821 is characterized for operation from –40°C to 85°C.

54ACT16821 . . . WD PACKAGE
74ACT16821 . . . DL PACKAGE
(TOP VIEW)

1OE	1	56	1CLK
1Q1	2	55	1D1
1Q2	3	54	1D2
GND	4	53	GND
1Q3	5	52	1D3
1Q4	6	51	1D4
V _{CC}	7	50	V _{CC}
1Q5	8	49	1D5
1Q6	9	48	1D6
1Q7	10	47	1D7
GND	11	46	GND
1Q8	12	45	1D8
1Q9	13	44	1D9
1Q10	14	43	1D10
2Q1	15	42	2D1
2Q2	16	41	2D2
2Q3	17	40	2D3
GND	18	39	GND
2Q4	19	38	2D4
2Q5	20	37	2D5
2Q6	21	36	2D6
V _{CC}	22	35	V _{CC}
2Q7	23	34	2D7
2Q8	24	33	2D8
GND	25	32	GND
2Q9	26	31	2D9
2Q10	27	30	2D10
2OE	28	29	2CLK



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

Copyright © 1996, Texas Instruments Incorporated

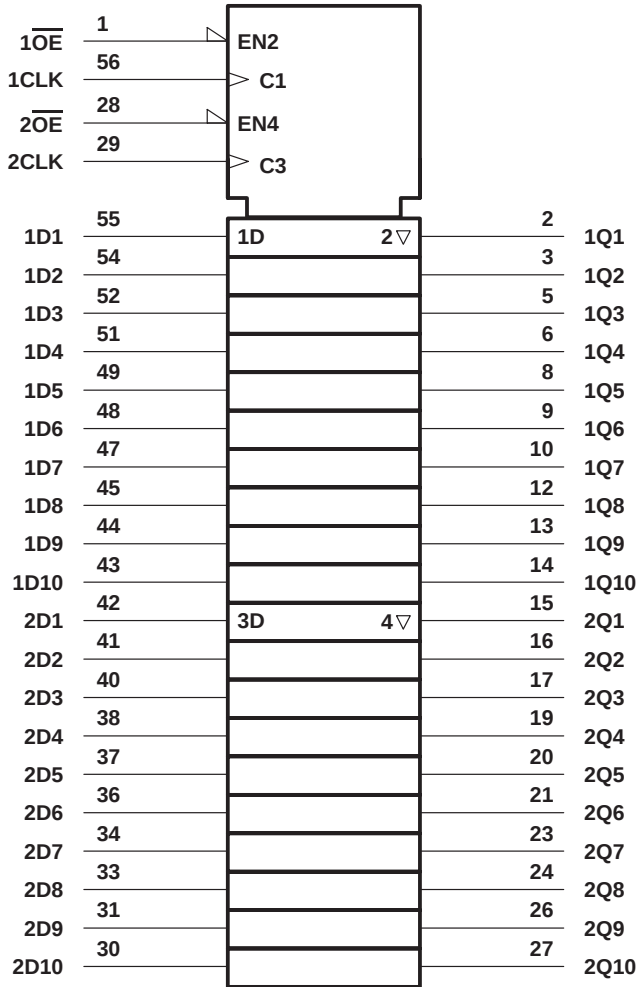
54ACT16821, 74ACT16821
20-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCAS176A – JANUARY 1991 – REVISED APRIL 1996

FUNCTION TABLE
(each 10-bit flip-flop)

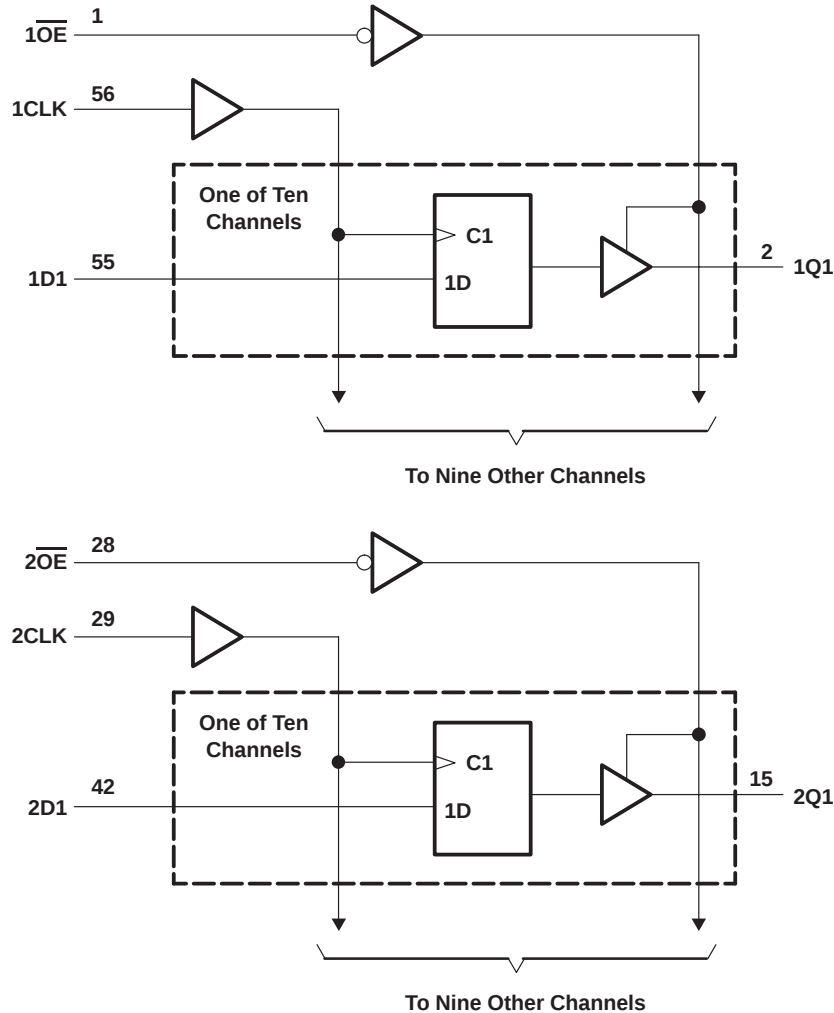
INPUTS			OUTPUT Q
OE	CLK	D	
L	↑	H	H
L	↑	L	L
L	H or L	X	Q ₀
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±500 mA
Maximum package power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

54ACT16821, 74ACT16821

20-BIT BUS-INTERFACE FLIP-FLOPS

WITH 3-STATE OUTPUTS

SCAS176A – JANUARY 1991 – REVISED APRIL 1996

recommended operating conditions (see Note 3)

		54ACT16821			74ACT16821			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
V _I	Input voltage	0		V _{CC}	0		V _{CC}	V
V _O	Output voltage	0		V _{CC}	0		V _{CC}	V
I _{OH}	High-level output current			–24			–24	mA
I _{OL}	Low-level output current			24			24	mA
Δt/Δv	Input transition rise or fall rate	0		10	0		10	ns/V
T _A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			54ACT16821		74ACT16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 μA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I _{OH} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I _{OH} = –75 mA [†]	5.5 V				3.85		3.85		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1	0.1		0.1		V
		5.5 V			0.1	0.1		0.1		
	I _{OL} = 24 mA	4.5 V			0.36	0.44		0.44		
		5.5 V			0.36	0.44		0.44		
	I _{OL} = 75 mA [†]	5.5 V				1.65		1.65		
I _I	V _I = V _{CC} or GND	5.5 V			±0.1	±1		±1		μA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.5	±5		±5		μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			8	80		80		μA
ΔI _{CC} [‡]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9	1		1		mA
C _i	V _I = V _{CC} or GND	5 V			3					pF
C _i	V _O = V _{CC} or GND	5 V			11					pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		54ACT16821		74ACT16821		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	0	70	0	70	0	70	MHz
t _w	Pulse duration, CLK high or low	7		7		7		ns
t _{su}	Setup time, data before CLK↑	7.5		7.5		7.5		ns
t _h	Hold time, data after CLK↑	0.5		0.5		0.5		ns

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

54ACT16821, 74ACT16821
20-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCAS176A – JANUARY 1991 – REVISED APRIL 1996

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			54ACT16821		74ACT16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			70			70		70		MHz
t_{PLH}	CLK	Any Q	4.5	8.8	12	4.5	13.4	4.5	13.4	ns
t_{PHL}			5.2	9.5	12.6	5.2	14	5.2	14	
t_{PZH}	$\overline{\text{OE}}$	Any Q	2.8	8.6	10.8	2.8	11.9	2.8	11.9	ns
t_{PZL}			4	9.7	13.3	4	14.7	4	14.7	
t_{PHZ}	$\overline{\text{OE}}$	Any Q	5.4	8.3	10	5.4	10.7	5.4	10.7	ns
t_{PLZ}			4.7	7.6	9.3	4.7	10	4.7	10	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	CL = 50 pF, f = 1 MHz		41	pF
		Outputs disabled			25	

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

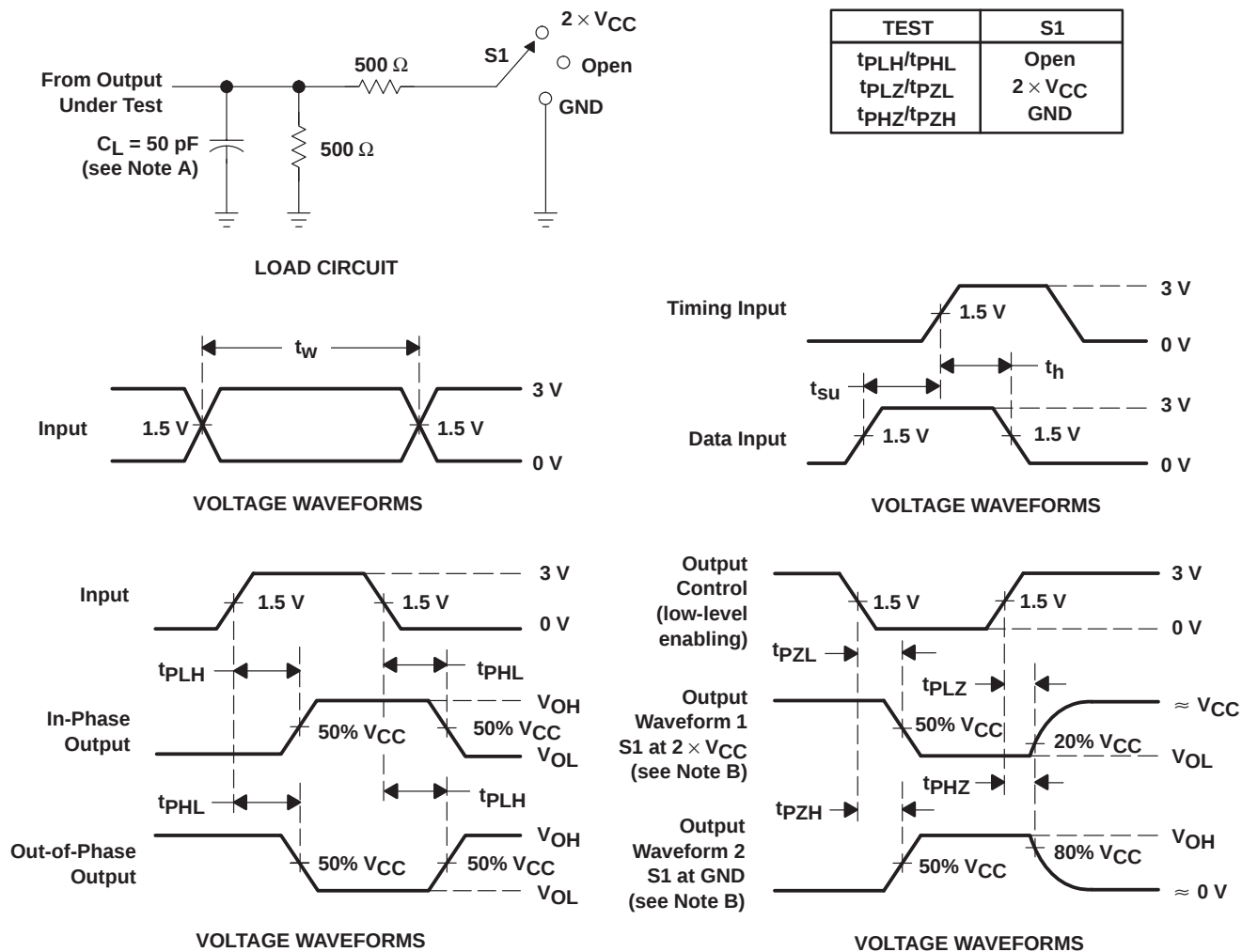


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
 POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

54ACT16821, 74ACT16821 20-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS176A – JANUARY 1991 – REVISED APRIL 1996

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT16821DL	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI
74ACT16821DLR	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

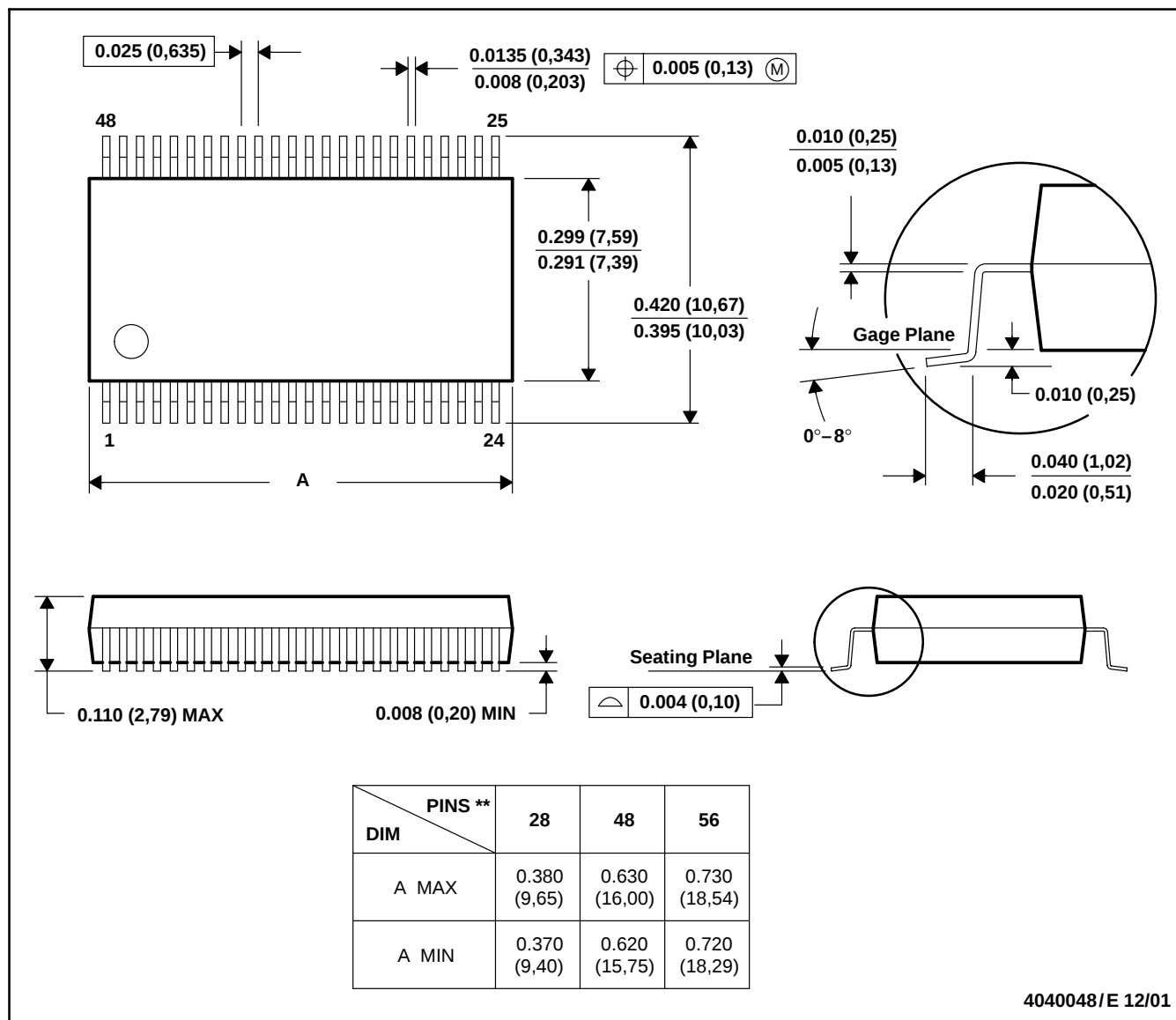
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2009, Texas Instruments Incorporated